ABSTRACT OF THE INVENTION

A sprayable adhesive composition having a viscosity within the range of 0.5 Pa.s to 5.0 Pa.s, containing at least one colored filler present in an amount up to 50% by weight of the adhesive composition, is suitable for marking identifications or fiducials on semiconductor dies or wafers. The preferred resins include epoxy resins or combinations of an electron donor resin and an electron acceptor resin,